



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Yuuichi TACHINO et al.

Group Art Unit: 1763

Serial No: 09/775,653

Examiner: Anna M. Crowell

Filed: February 5, 2001

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48A

PLASMA ETCHING METHOD AND APPARATUS

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AMENDMENT

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Assistant Commissioner for Patents Washington, D.C. 20231

TC 1700

Sir:

For:

This is responsive to the non-final Office Action mailed September 25, 2002, having a shortened period for response set to expire on December 25, 2002. A petition and fee for a ONE-month Extension of Time is enclosed, thereby extending the response period to January 25, 2003.

The following amendments and remarks are respectfully submitted.

IN THE CLAIMS:

Please AMEND claims 2, 3, 7, 10, 11, 13, 17 and 18, as follows. Also, please **ADD** new claims 21-23.

2. (ONCE MENDED) A plasma etching apparatus comprising:

a reaction tube made of a dielectric material in the form of a cylinder;

a high frequency coil antenna located around the reaction tube for generating a plasma inside the reaction tube, the high frequency coil antenna having a portion that produces a relatively large capacitive coupling with the reaction tube, a power supply terminal connected to a plasma source high frequency gower supply, and a ground terminal connected to a ground;

and 01/28/2003 CCHAU1

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03 FC:1202

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